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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	26
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	28-LCC (J-Lead)
Supplier Device Package	28-PLCC (11.48x11.48)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc932a1fa-129

4. Block diagram

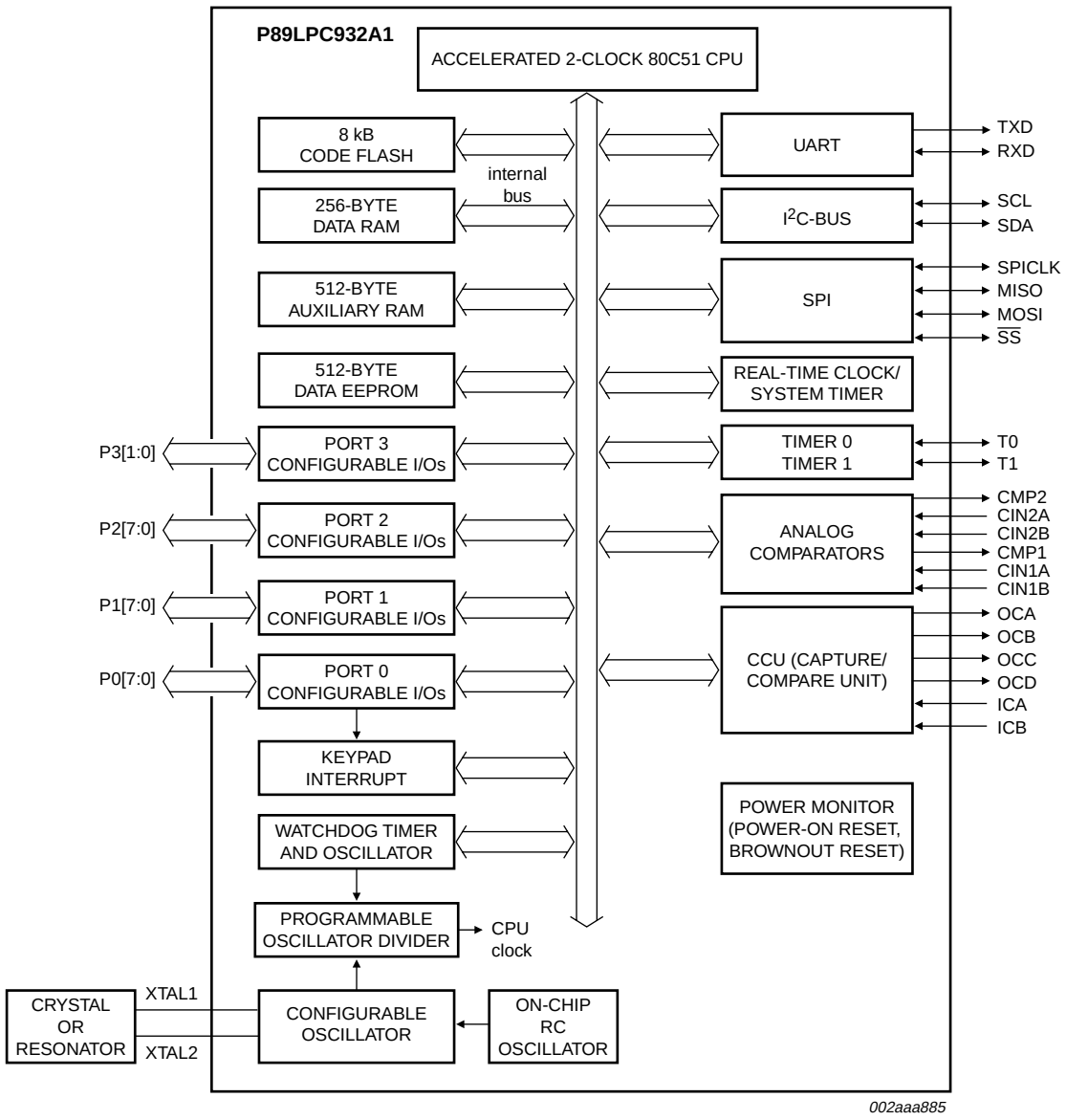


Fig 1. Block diagram

Table 2. Pin description *...continued*

Symbol	Pin		Type	Description
	TSSOP28, PLCC28, DIP28	HVQFN28		
P1.5/$\overline{\text{RST}}$	6	2	I	**P1.5 —** Port 1 bit 5 (input only).
			I	**$\overline{\text{RST}}$ —** External Reset input during power-on or if selected via UCFG1. When functioning as a reset input, a LOW on this pin resets the microcontroller, causing I/O ports and peripherals to take on their default states, and the processor begins execution at address 0. Also used during a power-on sequence to force ISP mode. **When using an oscillator frequency above 12 MHz, the reset input function of P1.5 must be enabled. An external circuit is required to hold the device in reset at power-up until V_{DD} has reached its specified level. When system power is removed V_{DD} will fall below the minimum specified operating voltage. When using an oscillator frequency above 12 MHz, in some applications, an external brownout detect circuit may be required to hold the device in reset when V_{DD} falls below the minimum specified operating voltage.**
P1.6/OCB	5	1	I/O	**P1.6 —** Port 1 bit 6.
			O	**OCB —** Output Compare B.
P1.7/OCC	4	28	I/O	**P1.7 —** Port 1 bit 7.
			O	**OCC —** Output Compare C.
P2.0 to P2.7			I/O	**Port 2:** Port 2 is an 8-bit I/O port with a user-configurable output type. During reset Port 2 latches are configured in the input only mode with the internal pull-up disabled. The operation of Port 2 pins as inputs and outputs depends upon the port configuration selected. Each port pin is configured independently. Refer to Section 7.13.1 “Port configurations” and Table 8 “Static characteristics” for details. All pins have Schmitt trigger inputs. Port 2 also provides various special functions as described below:
P2.0/ICB	1	25	I/O	**P2.0 —** Port 2 bit 0.
			I	**ICB —** Input Capture B.
P2.1/OCD	2	26	I/O	**P2.1 —** Port 2 bit 1.
			O	**OCD —** Output Compare D.
P2.2/MOSI	13	9	I/O	**P2.2 —** Port 2 bit 2.
			I/O	**MOSI —** SPI master out slave in. When configured as master, this pin is output; when configured as slave, this pin is input.
P2.3/MISO	14	10	I/O	**P2.3 —** Port 2 bit 3.
			I/O	**MISO —** When configured as master, this pin is input, when configured as slave, this pin is output.
P2.4/$\overline{\text{SS}}$	15	11	I/O	**P2.4 —** Port 2 bit 4.
			I	**$\overline{\text{SS}}$ —** SPI Slave select.
P2.5/SPICLK	16	12	I/O	**P2.5 —** Port 2 bit 5.
			I/O	**SPICLK —** SPI clock. When configured as master, this pin is output; when configured as slave, this pin is input.
P2.6/OCA	27	23	I/O	**P2.6 —** Port 2 bit 6.
			O	**OCA —** Output Compare A.

Table 3. Special function registers *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
TISE2	CCU interrupt status encode register	DEH	-	-	-	-	-	ENCINT.2	ENCINT.1	ENCINT.0	00	xxxx x000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TL2	CCU timer low	CCH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
TOR2H	CCU reload register high	CFH									00	0000 0000
TOR2L	CCU reload register low	CEH									00	0000 0000
TPCR2H	Prescaler control register high	CBH	-	-	-	-	-	-	TPCR2H.1	TPCR2H.0	00	xxxx xx00
TPCR2L	Prescaler control register low	CAH	TPCR2L.7	TPCR2L.6	TPCR2L.5	TPCR2L.4	TPCR2L.3	TPCR2L.2	TPCR2L.1	TPCR2L.0	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0		[5] [4]
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK		[6] [4]
WDL	Watchdog load	C1H									FF	1111 1111
WFEED1	Watchdog feed 1	C2H										
WFEED2	Watchdog feed 2	C3H										

[1] BRGR1 and BRGR0 must only be written if BRGEN in BRGCON SFR is logic 0. If any are written while BRGEN = 1, the result is unpredictable.

[2] All ports are in input only (high-impedance) state after power-up.

[3] The RSTSRC register reflects the cause of the P89LPC932A1 reset. Upon a power-up reset, all reset source flags are cleared except POF and BOF; the power-on reset value is xx11 0000.

[4] The only reset source that affects these SFRs is power-on reset.

[5] On power-on reset, the TRIM SFR is initialized with a factory preprogrammed value. Other resets will not cause initialization of the TRIM register.

[6] After reset, the value is 1110 01x1, i.e., PRE2 to PRE0 are all logic 1, WDRUN = 1 and WDCLK = 1. WDTOF bit is logic 1 after watchdog reset and is logic 0 after power-on reset. Other resets will not affect WDTOF.

7.2 Enhanced CPU

The P89LPC932A1 uses an enhanced 80C51 CPU which runs at six times the speed of standard 80C51 devices. A machine cycle consists of two CPU clock cycles, and most instructions execute in one or two machine cycles.

7.3 Clocks

7.3.1 Clock definitions

The P89LPC932A1 device has several internal clocks as defined below:

OSCCLK — Input to the DIVM clock divider. OSCCLK is selected from one of four clock sources (see Figure 7) and can also be optionally divided to a slower frequency (see Section 7.8 “CCLK modification: DIVM register”).

Note: f_{osc} is defined as the OSCCLK frequency.

CCLK — CPU clock; output of the clock divider. There are two CCLK cycles per machine cycle, and most instructions are executed in one to two machine cycles (two or four CCLK cycles).

RCCLK — The internal 7.373 MHz RC oscillator output.

PCLK — Clock for the various peripheral devices and is $^{CCLK}/_{2}$.

7.3.2 CPU clock (OSCCLK)

The P89LPC932A1 provides several user-selectable oscillator options in generating the CPU clock. This allows optimization for a range of needs from high precision to lowest possible cost. These options are configured when the flash is programmed and include an on-chip watchdog oscillator, an on-chip RC oscillator, an oscillator using an external crystal, or an external clock source. The crystal oscillator can be optimized for low, medium, or high frequency crystals covering a range from 20 kHz to 18 MHz.

7.3.3 Low speed oscillator option

This option supports an external crystal in the range of 20 kHz to 100 kHz. Ceramic resonators are also supported in this configuration.

7.3.4 Medium speed oscillator option

This option supports an external crystal in the range of 100 kHz to 4 MHz. Ceramic resonators are also supported in this configuration.

7.3.5 High speed oscillator option

This option supports an external crystal in the range of 4 MHz to 18 MHz. Ceramic resonators are also supported in this configuration.

7.3.6 Clock output

The P89LPC932A1 supports a user-selectable clock output function on the XTAL2/CLKOUT pin when crystal oscillator is not being used. This condition occurs if another clock source has been selected (on-chip RC oscillator, watchdog oscillator, external clock input on X1) and if the RTC is not using the crystal oscillator as its clock source. This allows external devices to synchronize to the P89LPC932A1. This output is enabled by the ENCLK bit in the TRIM register.

7.17.2 Mode 1

Mode 1 is the same as Mode 0, except that all 16 bits of the timer register are used.

7.17.3 Mode 2

Mode 2 configures the Timer register as an 8-bit Counter with automatic reload. Mode 2 operation is the same for Timer 0 and Timer 1.

7.17.4 Mode 3

When Timer 1 is in Mode 3 it is stopped. Timer 0 in Mode 3 forms two separate 8-bit counters and is provided for applications that require an extra 8-bit timer. When Timer 1 is in Mode 3 it can still be used by the serial port as a baud rate generator.

7.17.5 Mode 6

In this mode, the corresponding timer can be changed to a PWM with a full period of 256 timer clocks.

7.17.6 Timer overflow toggle output

Timers 0 and 1 can be configured to automatically toggle a port output whenever a timer overflow occurs. The same device pins that are used for the T0 and T1 count inputs are also used for the timer toggle outputs. The port outputs will be a logic 1 prior to the first timer overflow when this mode is turned on.

7.18 RTC/system timer

The P89LPC932A1 has a simple RTC that allows a user to continue running an accurate timer while the rest of the device is powered-down. The RTC can be a wake-up or an interrupt source. The RTC is a 23-bit down counter comprised of a 7-bit prescaler and a 16-bit loadable down counter. When it reaches all logic 0s, the counter will be reloaded again and the RTCF flag will be set. The clock source for this counter can be either the CCLK or the XTAL oscillator, provided that the XTAL oscillator is not being used as the CPU clock. If the XTAL oscillator is used as the CPU clock, then the RTC will use CCLK as its clock source. Only power-on reset will reset the RTC and its associated SFRs to the default state.

7.19.7 Alternating output mode

In asymmetrical mode, the user can set up PWM channels A/B and C/D as alternating pairs for bridge drive control. In this mode the output of these PWM channels are alternately gated on every counter cycle.

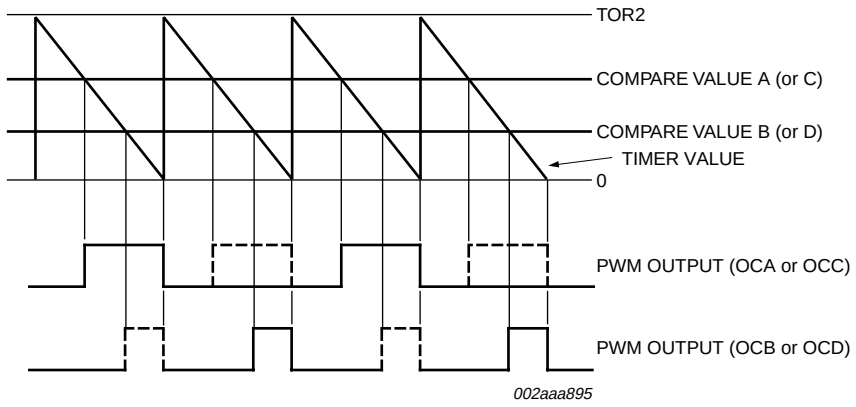


Fig 11. Alternate output mode

7.19.8 PLL operation

The PWM module features a PLL that can be used to generate a CCUCLK frequency between 16 MHz and 32 MHz. At this frequency the PWM module provides ultrasonic PWM frequency with 10-bit resolution provided that the crystal frequency is 1 MHz or higher. The PLL is fed an input signal from 0.5 MHz to 1 MHz and generates an output signal of 32 times the input frequency. This signal is used to clock the timer. The user will have to set a divider that scales PCLK by a factor from 1 to 16. This divider is found in the SFR register TCR21. The PLL frequency can be expressed as shown in Equation 1.

$$\text{PLL frequency} = \frac{\text{PCLK}}{(N+1)} \quad (1)$$

Where: N is the value of PLLDV[3:0].

Since N ranges from 0 to 15, the CCLK frequency can be in the range of PCLK to $^{PCLK}/_{16}$.

7.19.9 CCU interrupts

There are seven interrupt sources on the CCU which share a common interrupt vector.

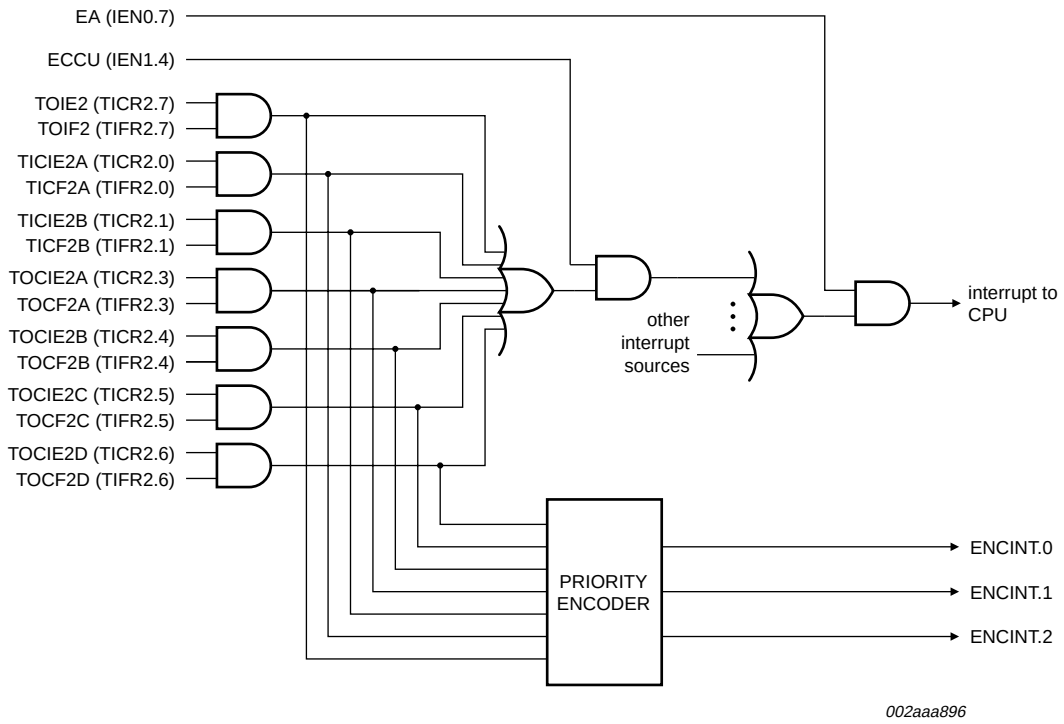


Fig 12. Capture/compare unit interrupts

7.20 UART

The P89LPC932A1 has an enhanced UART that is compatible with the conventional 80C51 UART except that Timer 2 overflow cannot be used as a baud rate source. The P89LPC932A1 does include an independent Baud Rate Generator. The baud rate can be selected from the oscillator (divided by a constant), Timer 1 overflow, or the independent Baud Rate Generator. In addition to the baud rate generation, enhancements over the standard 80C51 UART include Framing Error detection, automatic address recognition, selectable double buffering and several interrupt options. The UART can be operated in four modes: shift register, 8-bit UART, 9-bit UART, and CPU clock/32 or CPU clock/16.

7.20.1 Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted or received, LSB first. The baud rate is fixed at $^{1}/_{16}$ of the CPU clock frequency.

7.20.2 Mode 1

10 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), and a stop bit (logic 1). When data is received, the stop bit is stored in RB8 in Special Function Register SCON. The baud rate is variable and is determined by the Timer 1 overflow rate or the Baud Rate Generator (described in Section 7.20.5 “Baud rate generator and selection”).

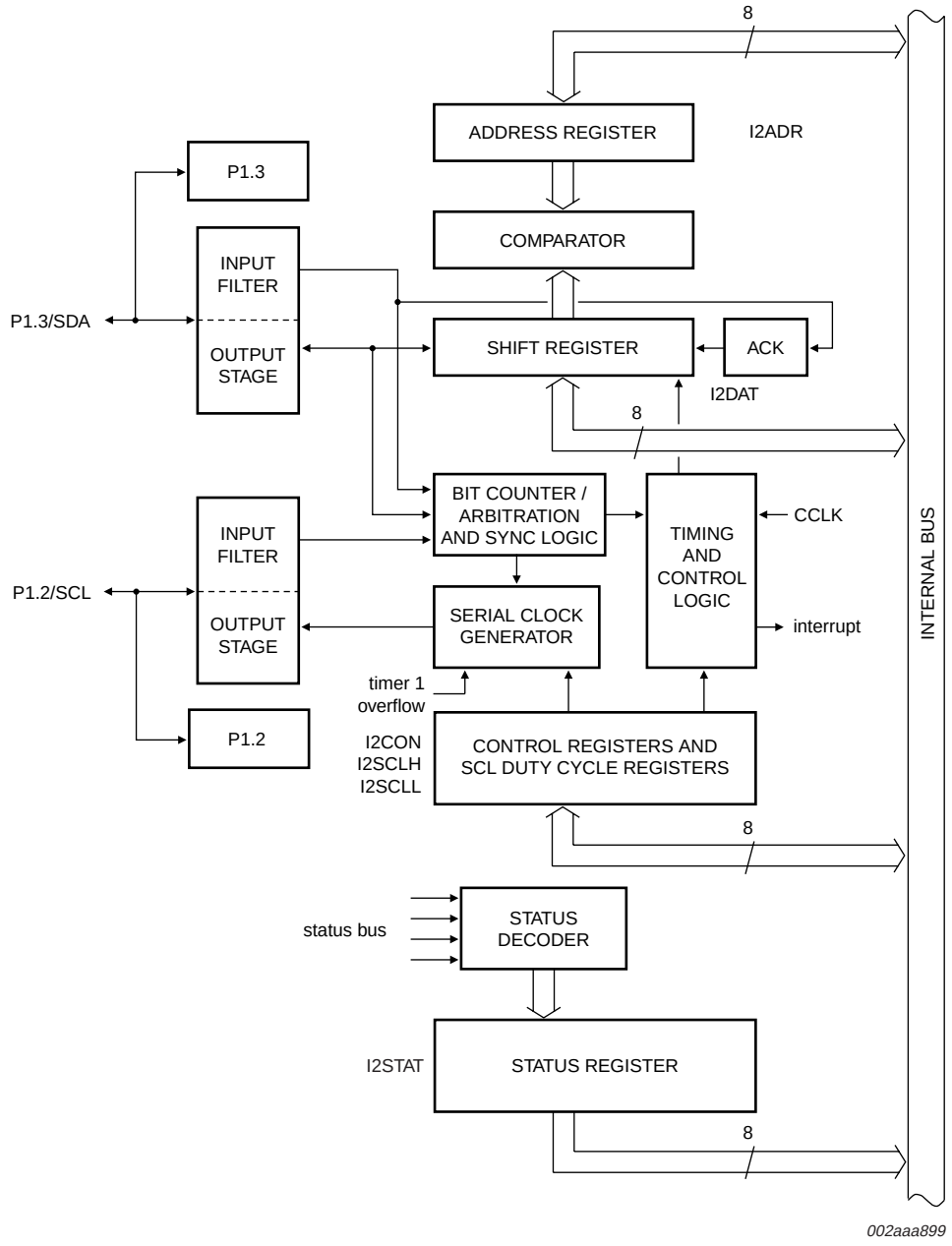


Fig 15. I²C-bus serial interface block diagram

7.22.1 Typical SPI configurations

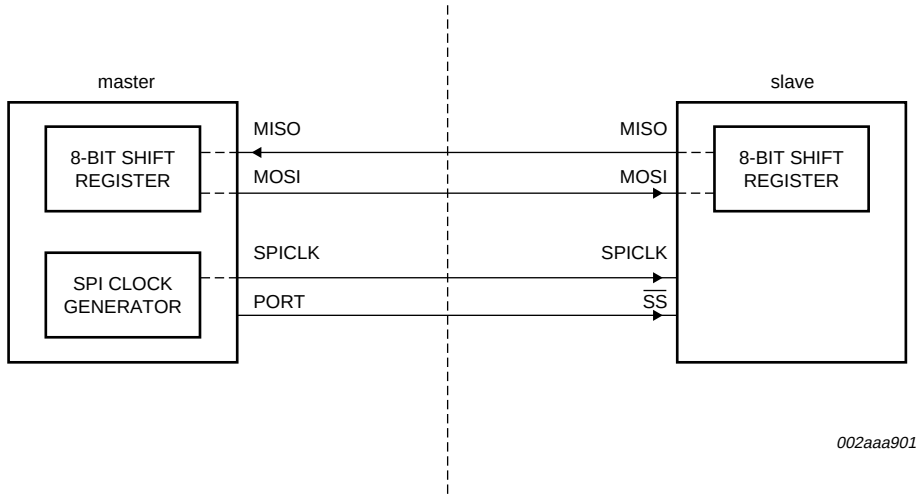


Fig 17. SPI single master single slave configuration

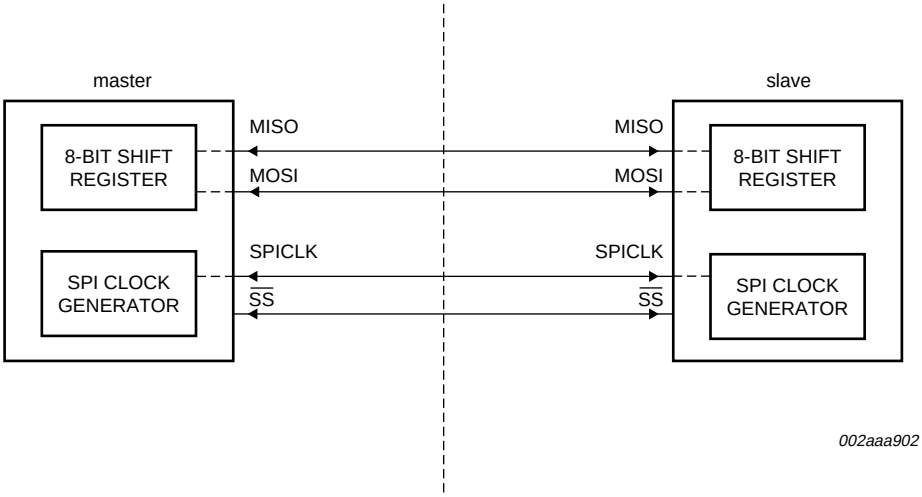


Fig 18. SPI dual device configuration, where either can be a master or a slave

7.23.3 Comparators and power reduction modes

Either or both comparators may remain enabled when Power-down or Idle mode is activated, but both comparators are disabled automatically in Total Power-down mode.

If a comparator interrupt is enabled (except in Total Power-down mode), a change of the comparator output state will generate an interrupt and wake up the processor. If the comparator output to a pin is enabled, the pin should be configured in the push-pull mode in order to obtain fast switching times while in Power-down mode. The reason is that with the **oscillator** stopped, the temporary strong pull-up that normally occurs during switching on a quasi-bidirectional port pin does not take place.

Comparators consume power in Power-down and Idle modes, as well as in the normal operating mode. This fact should be taken into account when system power consumption is an issue. To minimize power consumption, the user can disable the comparators via PCONA.5, or put the device in Total Power-down mode.

7.24 Keypad interrupt

The Keypad Interrupt function is intended primarily to allow a single interrupt to be generated when Port 0 is equal to or not equal to a certain pattern. This function can be used for bus address recognition or keypad recognition. The user can configure the port via SFRs for different tasks.

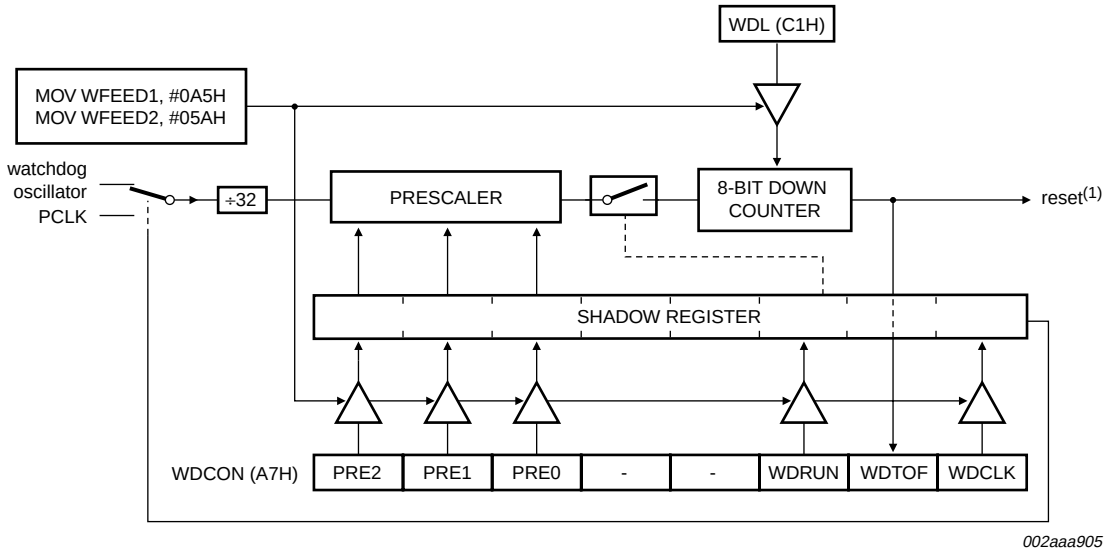
The Keypad Interrupt Mask Register (KBMASK) is used to define which input pins connected to Port 0 can trigger the interrupt. The Keypad Pattern Register (KBPATN) is used to define a pattern that is compared to the value of Port 0. The Keypad Interrupt Flag (KBIF) in the Keypad Interrupt Control Register (KBCON) is set when the condition is matched while the Keypad Interrupt function is active. An interrupt will be generated if enabled. The PATN_SEL bit in the Keypad Interrupt Control Register (KBCON) is used to define equal or not-equal for the comparison.

In order to use the Keypad Interrupt as an original KBI function like in 87LPC76x series, the user needs to set KBPATN = 0FFH and PATN_SEL = 1 (not equal), then any key connected to Port 0 which is enabled by the KBMASK register will cause the hardware to set KBIF and generate an interrupt if it has been enabled. The interrupt may be used to wake up the CPU from Idle or Power-down modes. This feature is particularly useful in handheld, battery-powered systems that need to carefully manage power consumption yet also need to be convenient to use.

In order to set the flag and cause an interrupt, the pattern on Port 0 must be held longer than six CCLKs.

7.25 Watchdog timer

The watchdog timer causes a system reset when it underflows as a result of a failure to feed the timer prior to the timer reaching its terminal count. It consists of a programmable 12-bit prescaler, and an 8-bit down counter. The down counter is decremented by a tap taken from the prescaler. The clock source for the prescaler is either the PCLK or the nominal 400 kHz watchdog oscillator. The watchdog timer can only be reset by a power-on reset. When the watchdog feature is disabled, it can be used as an interval timer and may generate an interrupt. Figure 21 shows the watchdog timer in Watchdog mode. Feeding the watchdog requires a two-byte sequence. If PCLK is selected as the watchdog clock and the CPU is powered-down, the watchdog is disabled. The watchdog timer has a time-out period that ranges from a few µs to a few seconds. Please refer to the P89LPC932A1 *User manual* for more details.



(1) Watchdog reset can also be caused by an invalid feed sequence, or by writing to WDCON not immediately followed by a feed sequence.

Fig 21. Watchdog timer in Watchdog mode (WDTE = 1)

7.26 Additional features

7.26.1 Software reset

The SRST bit in AUXR1 gives software the opportunity to reset the processor completely, as if an external reset or watchdog reset had occurred. Care should be taken when writing to AUXR1 to avoid accidental software resets.

7.26.2 Dual data pointers

The dual Data Pointers (DPTR) provides two different Data Pointers to specify the address used with certain instructions. The DPS bit in the AUXR1 register selects one of the two Data Pointers. Bit 2 of AUXR1 is permanently wired as a logic 0 so that the DPS bit may be toggled (thereby switching Data Pointers) simply by incrementing the AUXR1 register, without the possibility of inadvertently altering other bits in the register.

7.27 Data EEPROM

The P89LPC932A1 has 512 B of on-chip data EEPROM. The data EEPROM is SFR based, byte readable, byte writable, and erasable (via row fill and sector fill). The user can read, write and fill the memory via SFRs and one interrupt. This data EEPROM provides 400000 minimum erase/program cycles for each byte.

- **Byte mode:** In this mode, data can be read and written one byte at a time.
- **Row fill:** In this mode, the addressed row (64 bytes) is filled with a single value. The entire row can be erased by writing 00H.
- **Sector fill:** In this mode, all 512 bytes are filled with a single value. The entire sector can be erased by writing 00H.

After the operation finishes, the hardware will set the EEIF bit, which if enabled will generate an interrupt. The flag is cleared by software.

7.28 Flash program memory

7.28.1 General description

The P89LPC932A1 flash memory provides in-circuit electrical erasure and programming. The flash can be erased, read, and written as bytes. The Sector and Page Erase functions can erase any flash sector (1 kB) or page (64 bytes). The Chip Erase operation will erase the entire program memory. ICP using standard commercial programmers is available. In addition, IAP and byte-erase allows code memory to be used for non-volatile data storage. On-chip erase and write timing generation contribute to a user-friendly programming interface. The P89LPC932A1 flash reliably stores memory contents even after 400000 erase and program cycles. The cell is designed to optimize the erase and programming mechanisms. The P89LPC932A1 uses V_{DD} as the supply voltage to perform the Program/Erase algorithms.

7.28.2 Features

- Programming and erase over the full operating voltage range.
- Byte erase allows code memory to be used for data storage.
- Read/Programming/Erase using ISP/IAP/ICP.
- Internal fixed boot ROM, containing low-level IAP routines available to user code.
- Default loader providing ISP via the serial port, located in upper end of user program memory.
- Boot vector allows user-provided flash loader code to reside anywhere in the flash memory space, providing flexibility to the user.
- Any flash program/erase operation in 2 ms.
- Programming with industry-standard commercial programmers.
- Programmable security for the code in the flash for each sector.
- 400000 typical erase/program cycles for each byte.
- 20 year minimum data retention.

7.28.3 Flash organization

The program memory consists of eight 1 kB sectors on the P89LPC932A1 device. Each sector can be further divided into 64-byte pages. In addition to sector erase, page erase, and byte erase, a 64-byte page register is included which allows from 1 byte to 64 bytes of a given page to be programmed at the same time, substantially reducing overall programming time.

7.28.4 Using flash as data storage

The flash code memory array of this device supports individual byte erasing and programming. Any byte in the code memory array may be read using the MOVC instruction, provided that the sector containing the byte has not been secured (a MOVC instruction is not allowed to read code memory contents of a secured sector). Thus any byte in a non-secured sector may be used for non-volatile data storage.

7.28.5 Flash programming and erasing

Four different methods of erasing or programming of the flash are available. The flash may be programmed or erased in the end-user application (IAP) under control of the application's firmware. Another option is to use the ICP mechanism. This ICP system provides for programming through a serial clock - serial data interface. As shipped from the factory, the upper 512 bytes of user code space contains a serial ISP routine allowing for the device to be programmed in circuit through the serial port. The flash may also be programmed or erased using a commercially available EPROM programmer which supports this device. This device does not provide for direct verification of code memory contents. Instead, this device provides a 32-bit CRC result on either a sector or the entire user code space.

7.28.6 In-circuit programming

ICP is performed without removing the microcontroller from the system. The ICP facility consists of internal hardware resources to facilitate remote programming of the P89LPC932A1 through a two-wire serial interface. The ICP facility has made ICP in an embedded application—using commercially available programmers—possible with a minimum of additional expense in components and circuit board area. The ICP function uses five pins. Only a small connector needs to be available to interface your application to a commercial programmer in order to use this feature. Additional details may be found in the P89LPC932A1 *User manual*.

7.28.7 In-application programming

IAP is performed in the application under the control of the microcontroller's firmware. The IAP facility consists of internal hardware resources to facilitate programming and erasing. The IAP facility has made IAP in an embedded application possible without additional components. Two methods are available to accomplish IAP. A set of predefined IAP functions are provided in a Boot ROM and can be called through a common interface, PGM_MTP. Several IAP calls are available for use by an application program to permit selective erasing and programming of flash sectors, pages, security bits, configuration bytes, and device ID. These functions are selected by setting up the microcontroller's registers before making a call to PGM_MTP at FF00H. The Boot ROM occupies the program memory space at the top of the address space from FF00H to FEFFH, thereby not conflicting with the user program memory space.

10.1 Waveforms

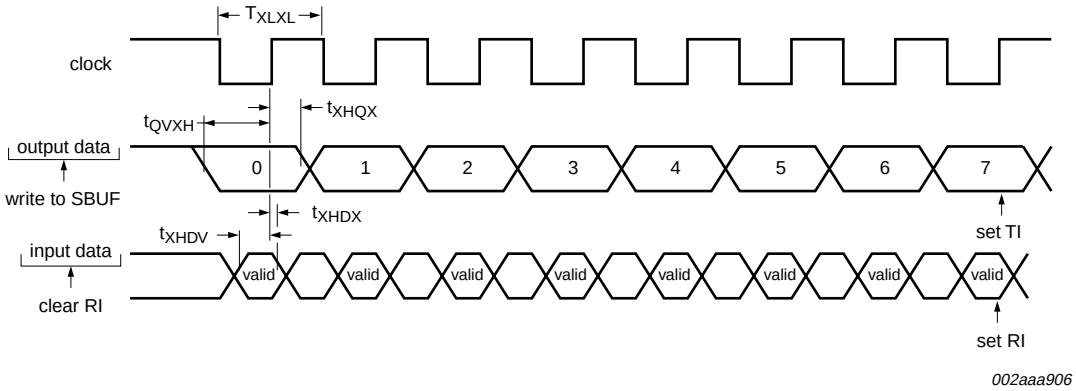


Fig 22. Shift register mode timing

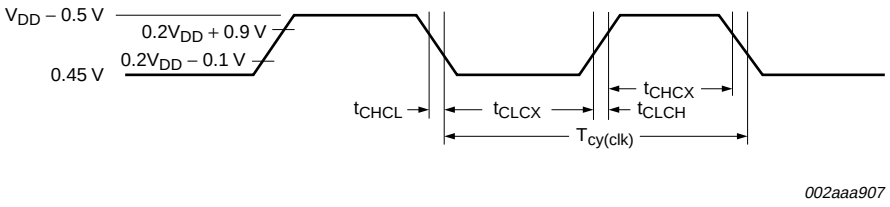


Fig 23. External clock timing

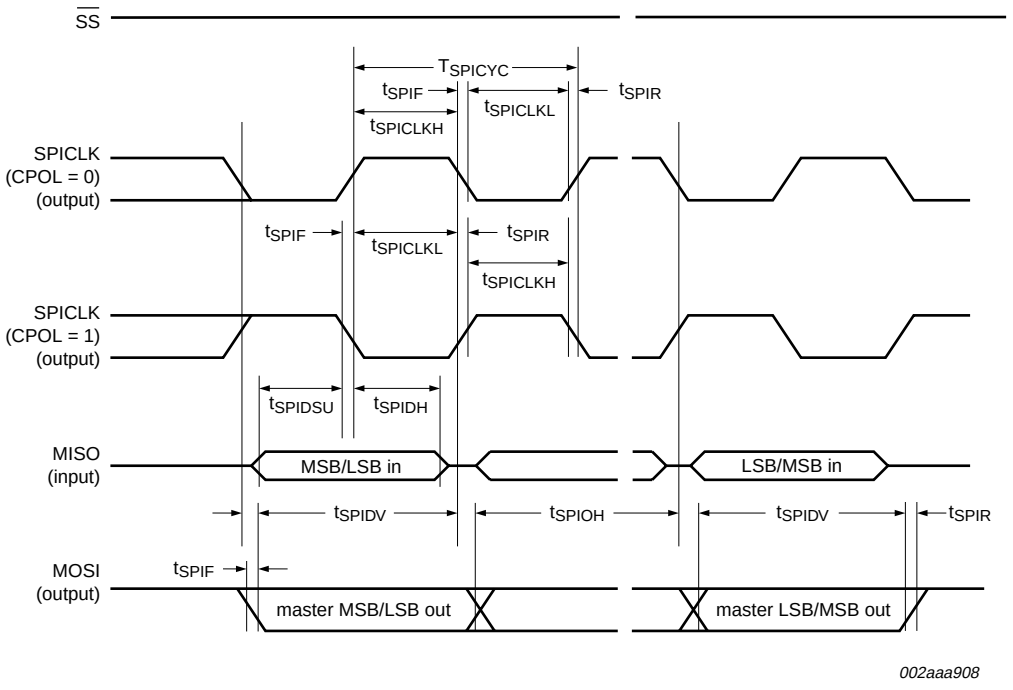


Fig 24. SPI master timing (CPHA = 0)

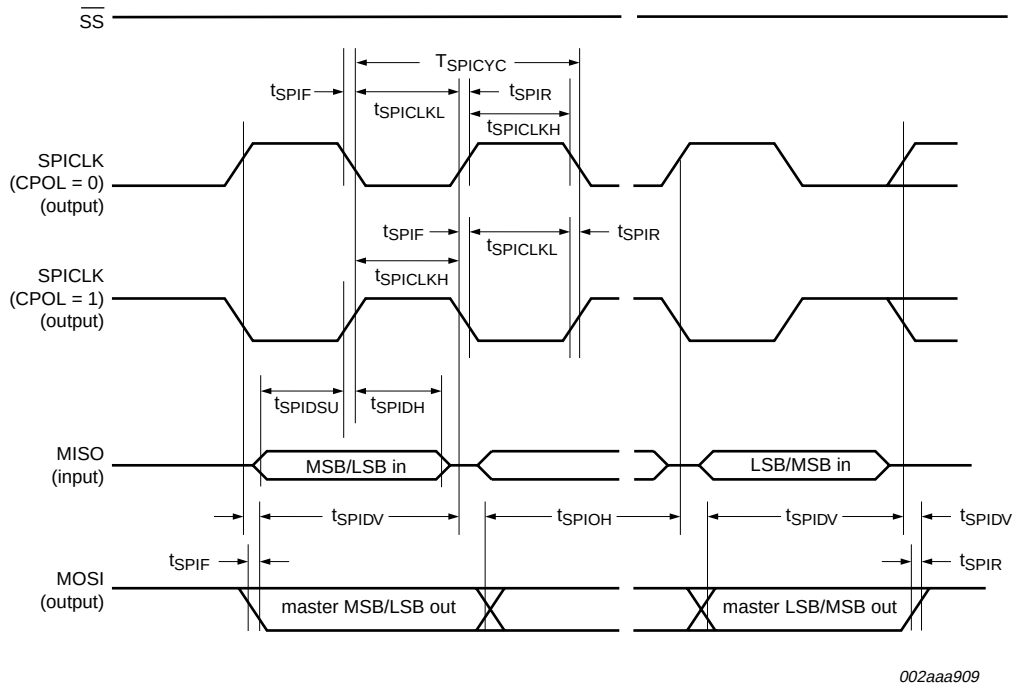


Fig 25. SPI master timing (CPHA = 1)

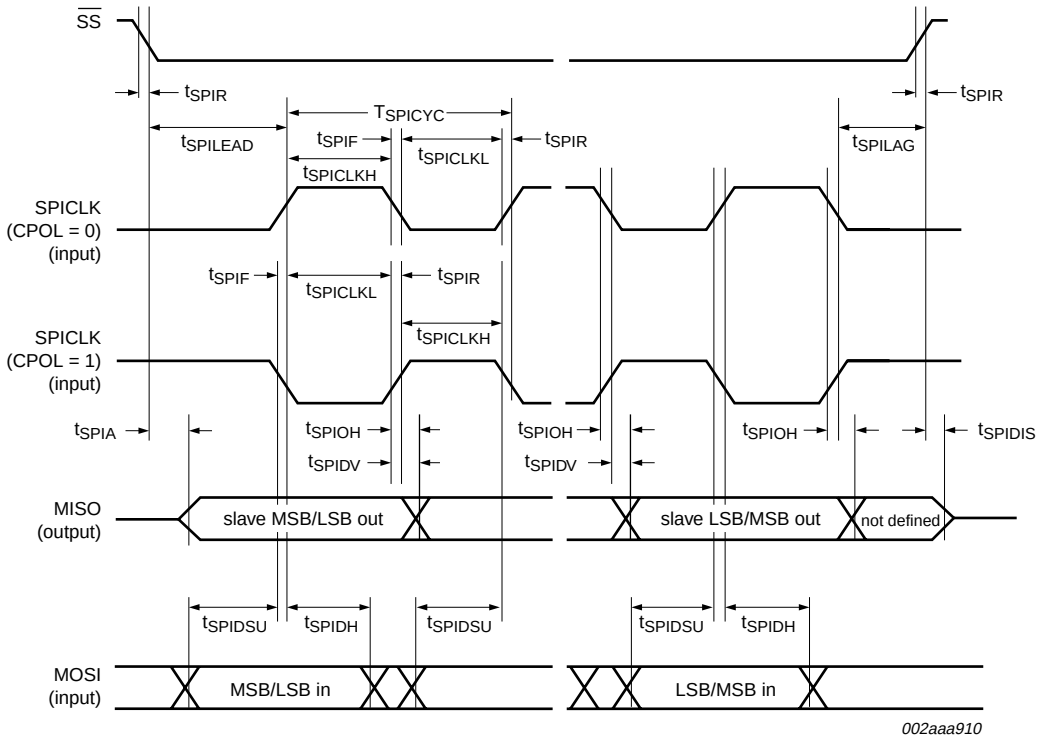
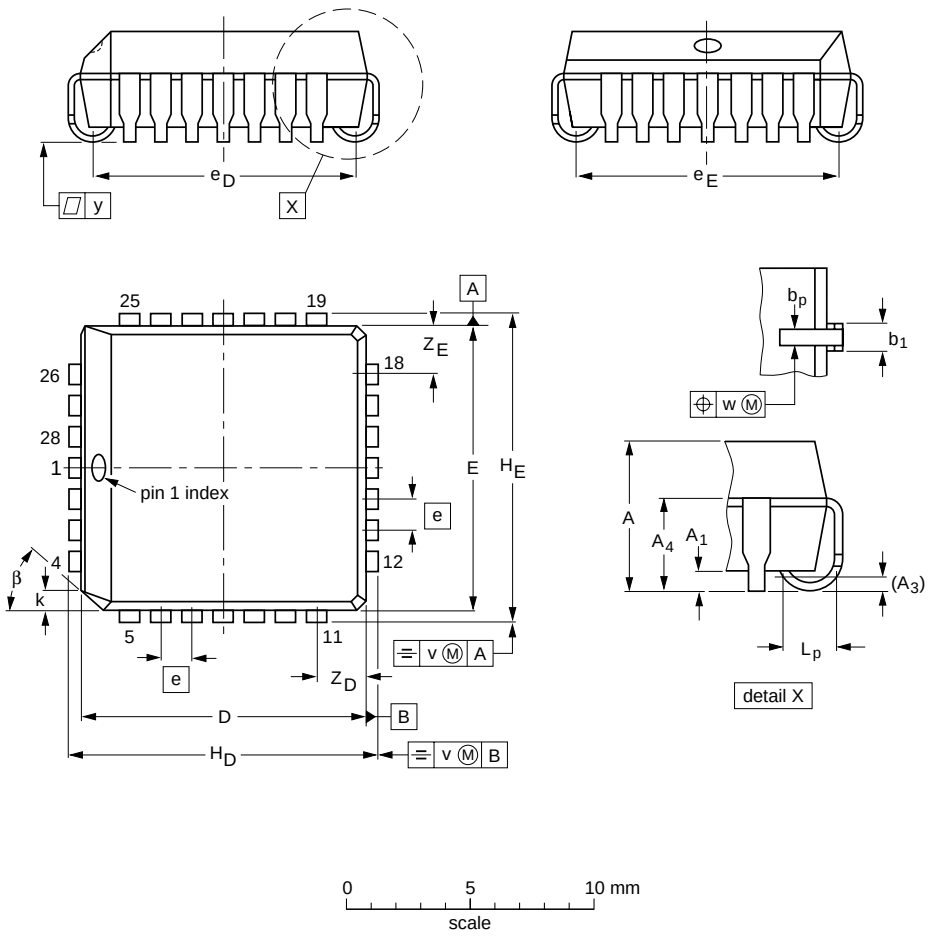


Fig 26. SPI slave timing (CPHA = 0)

12. Package outline

PLCC28: plastic leaded chip carrier; 28 leads **SOT261-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	11.58 11.43	11.58 11.43	1.27	10.92 9.91	10.92 9.91	12.57 12.32	12.57 12.32	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.456 0.450	0.456 0.450	0.05	0.43 0.39	0.43 0.39	0.495 0.485	0.495 0.485	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

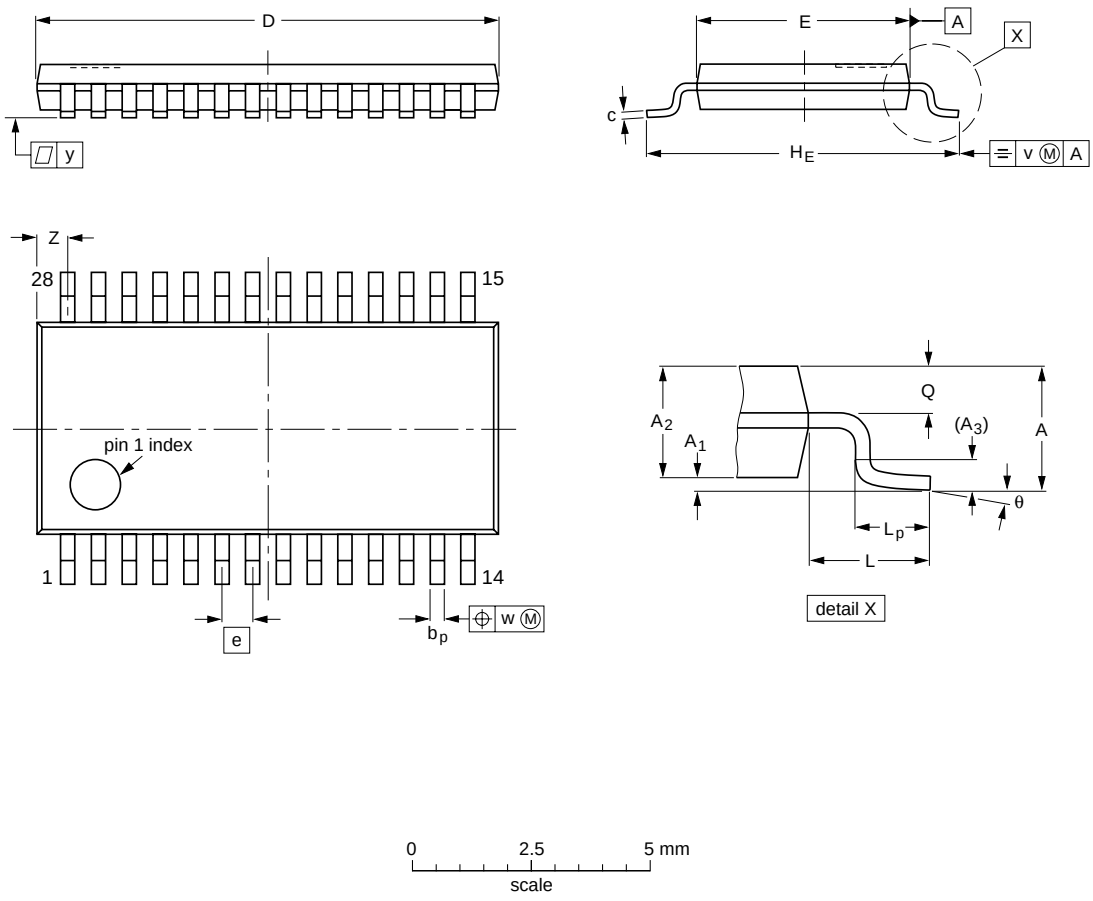
Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT261-2	112E08	MS-018	EDR-7319			~~99-12-27~~ 01-11-15

Fig 29. Package outline SOT261-2 (PLCC28)

TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm **SOT361-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	9.8 9.6	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.8 0.5	8^o 0^o

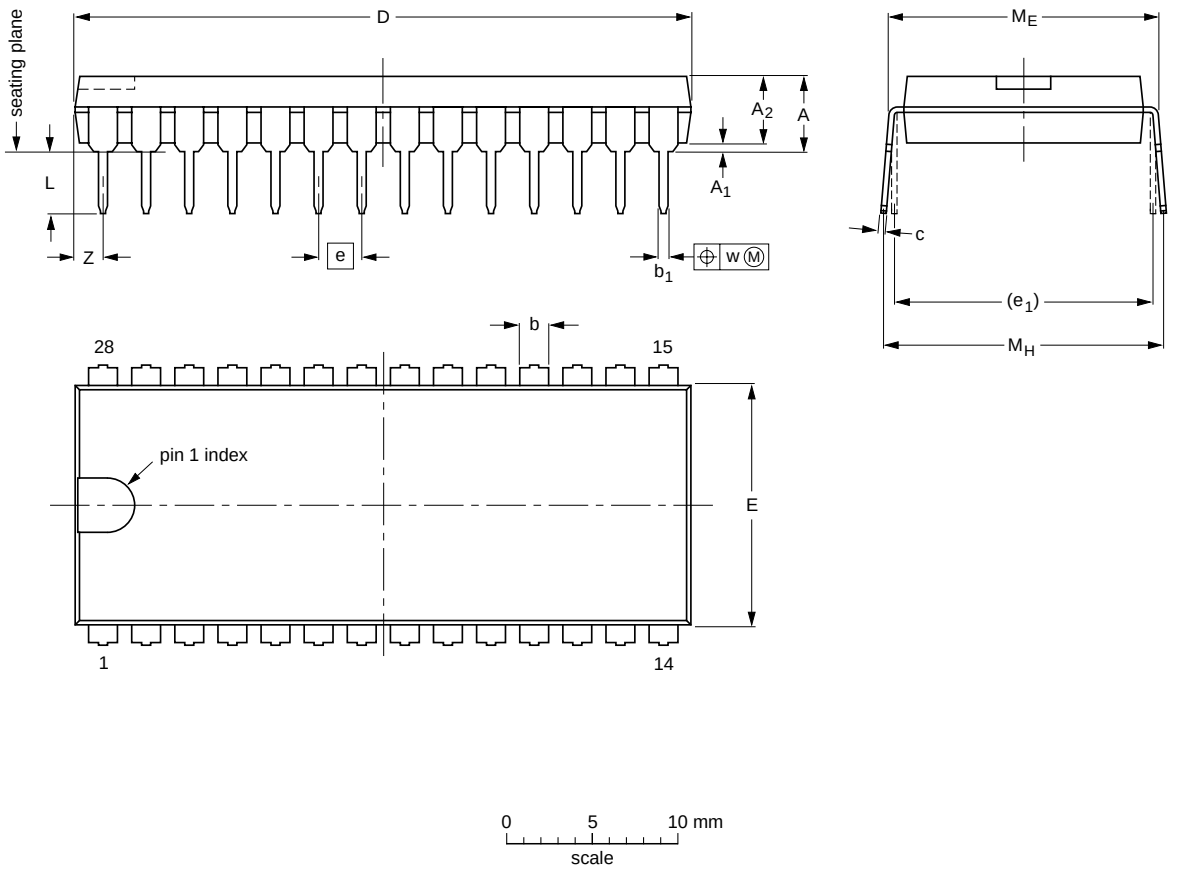
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT361-1		MO-153				~~99-12-27~~ 03-02-19

Fig 30. Package outline SOT361-1 (TSSOP28)

DIP28: plastic dual in-line package; 28 leads (600 mil) **SOT117-1**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	5.1	0.51	4	1.7 1.3	0.53 0.38	0.32 0.23	36 35	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	1.7
inches	0.2	0.02	0.16	0.066 0.051	0.020 0.014	0.013 0.009	1.41 1.34	0.56 0.54	0.1	0.6	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.067

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT117-1	051G05	MO-015	SC-510-28			~~99-12-27~~ 03-02-13

Fig 32. Package outline SOT117-1 (DIP28)

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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